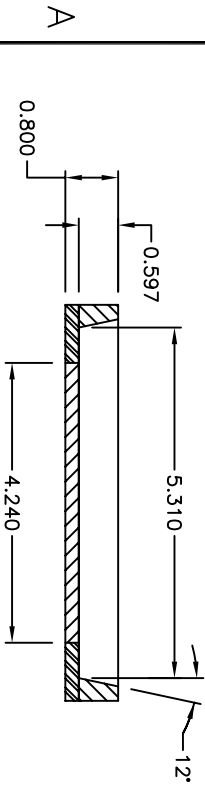
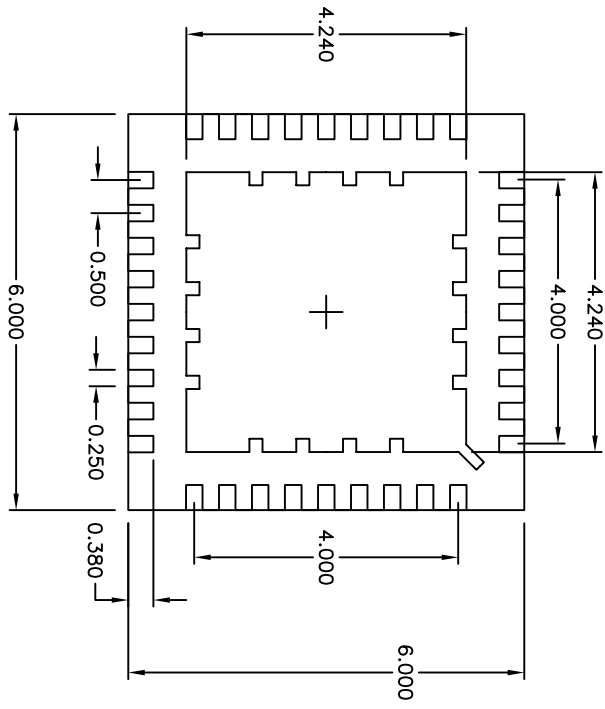
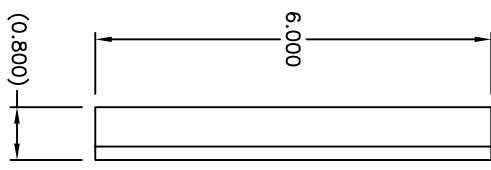
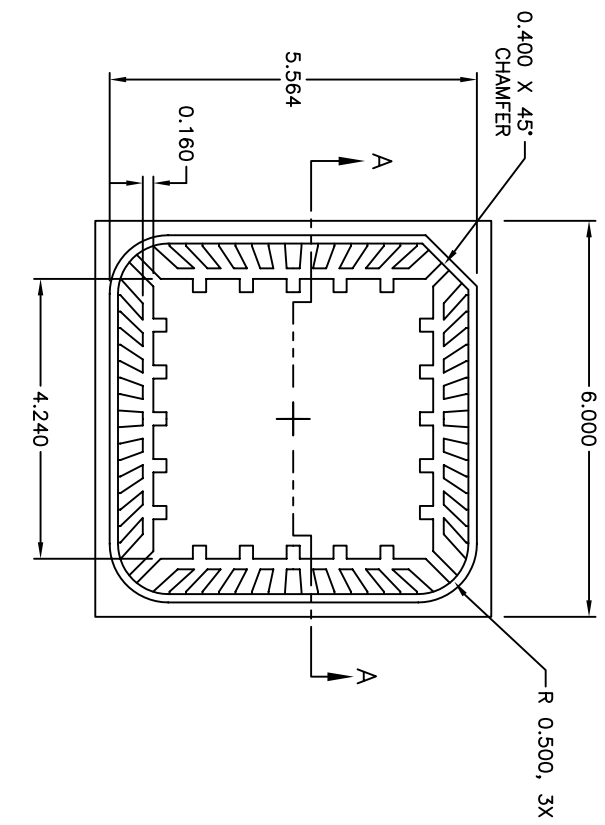


REVISIONS			
EON NO.	DATE	DESCRIPTION	APPROVED
10631	3/14/06	PRODUCTION RELEASE	D.BENANDIO



TOP VIEW

BOTTOM VIEW

SECTION A-A

- NOTES:
1. BODY: PLASTIC, SEMICONDUCTOR GRADE.
 3. LEAD FRAME: COPPER, 194 FH.
 4. LEAD FINISH: FULL GOLD PLATE.
 5. FRAME THICKNESS: 0.2030 ±.0076.
 6. DIE PAD: 4.240mm X 4.240mm.
 7. JEDEC OUTLINE: MO-220 (VJUD-4).

	THIRD ANGLE PROJECTION
UNLESS OTHERWISE SPECIFIED DIMENSIONS ARE IN MILLIMETERS	
XXX ± 0.015	XXXX ± ---
XXXX ± 0.050	ANGLES: ± 1°
DO NOT SCALE DRAWING	

DRAWN BY	GRIFFITTS	DATE	3/14/06
APP BY	P. FLASKERUD	DATE	3/14/06
CUSTOMER	---		
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SIZE	PART NO.
A	MLP6X6-36-OP-01
SCALE	NONE
FILE	MLP6X6-36-OP-01-R1.DWG
SHEET	1 OF 1